

Solder Pin – Foil – Multiple Crimp

Technical Features

Contact Material:

CuSn4

Contact Finish:

pre-tin plated,
selective gold plated on request

**Contact Resistance
(New State):**

CuSn4: $\leq 3 \text{ m}\Omega$

Total Temperature max.:*

-40 °C to +120 °C (tin plated)
-40 °C to +140 °C (gold plated)

Conductor Thickness:

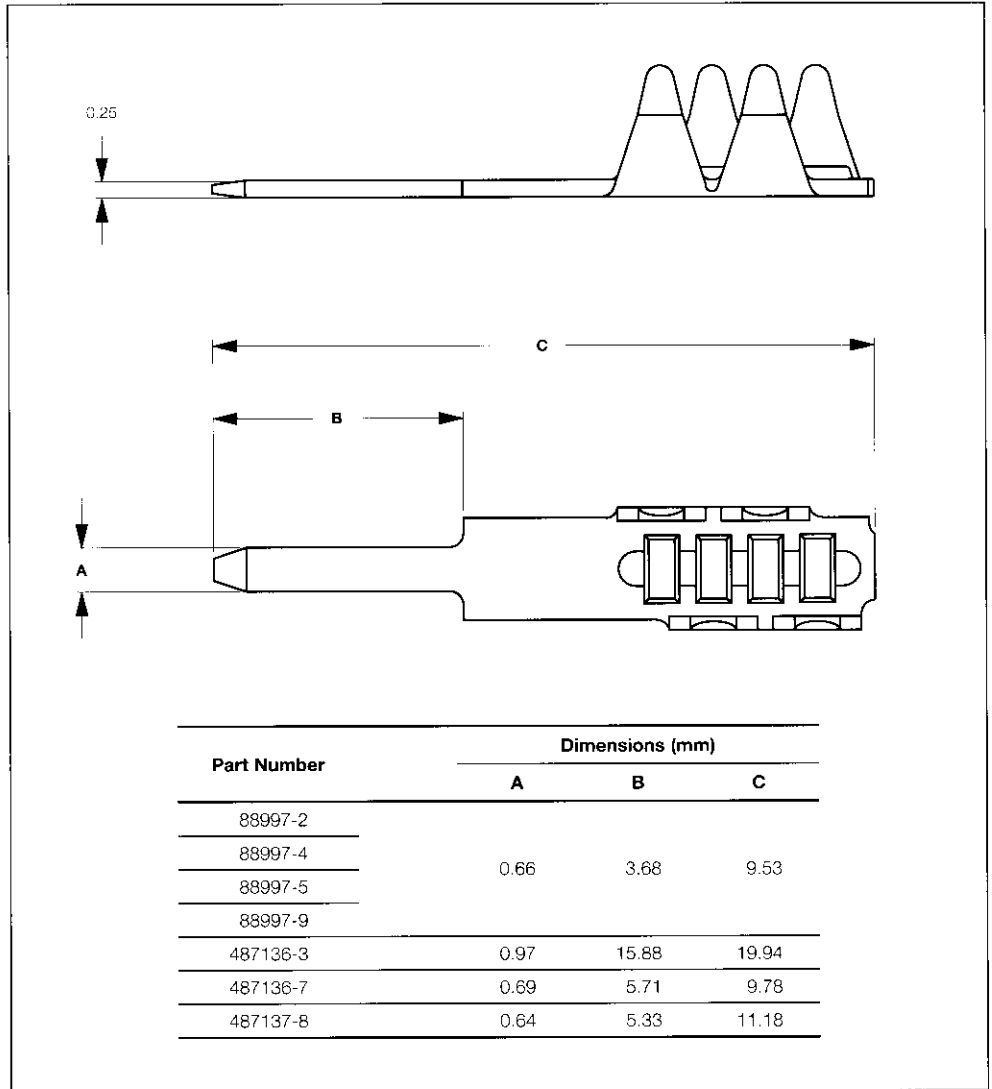
4-200 μm

Product Specification:

108-xxxxx

Application Specification:

114-16015



Multiple Crimp

Wire Size Range* (mm ²)	Insulation Diameter*		Material and Finish**	Part Numbers				Applicator	Hand Tool
	FLK (mm)	FLR (mm)		Strip Form	Packaging Unit	Loose-Piece	Packaging Unit		
-	-	-	1	88997-2	15,000				
-	-	-	2	88997-4	15,000			224910	
-	-	-	3	88997-5	15,000				
-	-	-	4	88997-9	15,000				90273-5
-	-	-	1	487136-3	15,000				
-	-	-	1	487136-7	15,000			318619	
-	-	-	1	487137-8	15,000				

*) Depending on Foil

**** Material and Finish:**

- 1 = Tin on solder area, crimp area tin plated
- 2 = 0.38 μm gold on solder area, crimp area tin plated
- 3 = 0.76 μm gold on solder area, crimp area tin plated
- 4 = Unplated on solder area, crimp area tin plated